

IN THE CLAIMS:

Claim 1 (currently amended)

1. A method of packaging a PVA sponge (for use in scrubbing semiconductor wafers, said method comprising:

(a) placing said sponge in a [container] flexible plastic bag;

(b) said sponge containing a quantity of de-ionized water with around 0.05% to substantially less than 1% by volume of hydrogen peroxide; and

(c) sealing said [container] bag.

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Claim 2 (withdrawn)

Claim 3 (previously amended)

3. A method as in Claim 1 in which said quantity of de-ionized water with hydrogen peroxide is between an amount sufficient to wet said sponge and an amount necessary to saturate said sponge.

Claim 4 (previously amended)

4. A method as in Claim 1 in which the volume of hydrogen peroxide is around 0.1%.

Claim 5 (currently amended)

A method of packaging a [cleaning article] PVA sponge brush, said method comprising placing said <sup>PVA sponge brush</sup> cleaning article in a [container] plastic bag, said [cleaning article] sponge brush

containing a quantity of de-ionized water, said water containing hydrogen peroxide in an amount effective to kill and retard the growth of bacteria in said <sup>sponge brush</sup> cleaning article but less than an amount sufficient to develop significant quantities of metallic ions in said <sup>plastic bag</sup> container, and sealing said <sup>plastic bag</sup> container, in which said amount of hydrogen peroxide is about 0.05% to substantially less than 1% by volume.

Claim 6 (withdrawn)

Claim 7 (withdrawn)

Claim 8 (withdrawn)

Claim 9 (currently amended)

A packaged [cleaning article] PVA sponge for use in clean rooms, said <sup>PVA sponge</sup> cleaning article having particulate, metal ion and anionic counts at or below the values specified for a clean room, said package comprising a sealed [container] flexible plastic bag, said [cleaning article] sponge being positioned in said [container] bag, and containing a quantity of de-ionized water, said de-ionized water containing hydrogen peroxide in a concentration effective to kill and retard the growth of bacteria in said [cleaning article] <sup>PVA</sup> sponge, said amount being low enough to substantially ensure decomposition of said hydrogen peroxide in a relatively short period of time after the

*bag*  
container is sealed and being between 0.05% and substantially  
less than 1% by volume.

Claim 10 (withdrawn)

Claim 11 (withdrawn)

Claim 12 (previously amended)

*LAB PVA sponge*  
12. A ~~cleaning~~ *pva sponge* article as in Claim 9 in which said  
*pva sponge* ~~cleaning article~~ is a ~~PVA sponge~~ for scrubbing semiconductor  
wafer surfaces, and said concentration of hydrogen peroxide is  
around 0.1 percent by volume.

Claim 13 (withdrawn)

Claim 14 (withdrawn)

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